This technology is currently not available for licensing

Tech ID: 29177

ADDITIONAL TECHNOLOGIES BY THESE INVENTORS

- Eliminating Misfit Dislocations with In-Situ Compliant Substrate Formation
- III-Nitride-Based Vertical Cavity Surface Emitting Laser (VCSEL) with a Dielectric P-Side Lens
- Methods to Produce and Recycle Substates for III-Nitride Materials with Electrochemical Etching
- III-Nitride Tunnel Junction with Modified Interface
- Novel Multilayer Structure for High-Efficiency UV and Far-UV Light-Emitting Devices
- A Method To Lift-Off Nitride Materials With Electrochemical Etch
- Activation of P-Type Layers of Tunnel Junctions in Micro-LEDs
- High-Intensity Solid State White Laser Diode
- Nitride Based Ultraviolet LED with an Ultraviolet Transparent Contact
- Epitaxial Light Control Features in Light Emitting Diodes
- High-Efficiency Vertical Cavity Surface Emitting Laser Fabrication
- A Wafer-Scale, Low Defect Density Strain Relaxed Template for III-Nitride-Based High Efficiency and High-Power Devices
- High-Efficiency and High-Power III-Nitride Devices Grown on or Above a Strain Relaxed Template
- III-Nitride Based VCSEL with Curved Mirror on P-Side of the Aperture

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